



US009543465B2

(12) **United States Patent**  
**Suzuki et al.**

(10) **Patent No.:** **US 9,543,465 B2**  
(45) **Date of Patent:** **Jan. 10, 2017**

(54) **METHOD FOR MANUFACTURING LIGHT  
EMITTING DEVICE**

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(\*) Notice: Subject to any disclaimer, the term of this  
patent is extended or adjusted under 35  
U.S.C. 154(b) by 0 days.

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al., filed Dec. 12, 2014, entitled Light Emitting Device.

(22) Filed: **May 19, 2015**

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(65) **Prior Publication Data**

US 2015/0340546 A1 Nov. 26, 2015

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(30) **Foreign Application Priority Data**

May 20, 2014 (JP) ..... 2014-104248  
Jan. 30, 2015 (JP) ..... 2015-017629

(57) **ABSTRACT**

A method for manufacturing a light emitting device has:  
preparing a base body which comprises a pair of connection  
terminals; preparing a light emitting element which includes  
a substrate, a semiconductor laminate that is laminated on  
the substrate, and a pair of electrodes formed on the surface  
of the semiconductor laminate; joining the electrodes of the  
light emitting element to the connection terminals of the  
base body; covering the light emitting element with a sealing  
member; and removing at least a part of the sealing member  
and a part of the substrate of the light emitting element from  
the opposite side from the base body so that an upper surface  
of the sealing member is lower than an upper surface of the  
substrate of the light emitting element.

(51) **Int. Cl.**  
**H01L 33/00** (2010.01)

(52) **U.S. Cl.**  
CPC ..... **H01L 33/0079** (2013.01); **H01L 2933/005**  
(2013.01); **H01L 2933/0041** (2013.01)

(58) **Field of Classification Search**  
None  
See application file for complete search history.

**11 Claims, 10 Drawing Sheets**

